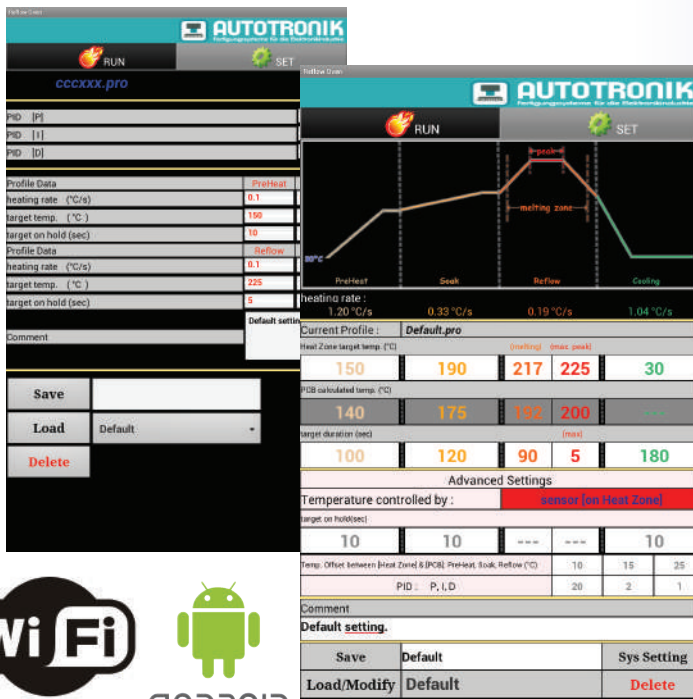
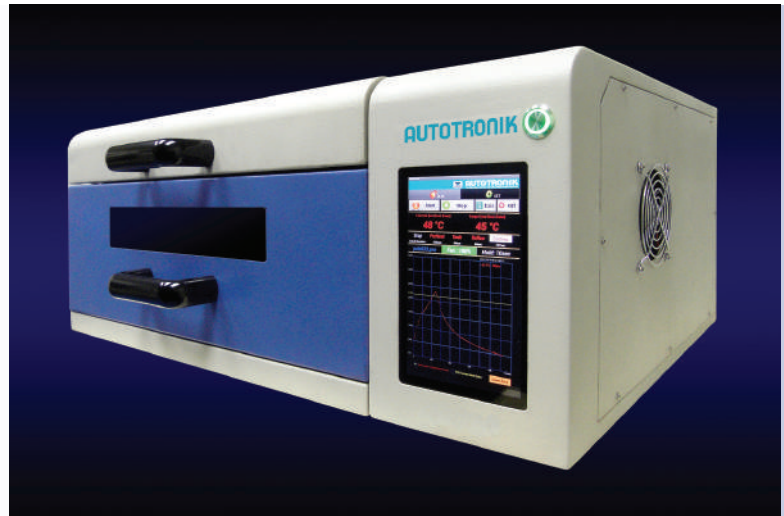


Bench-top / Batch Reflow Oven

BT301

Dynamic Thermal Profile using a Batch Reflow Oven with Android™ Operating System

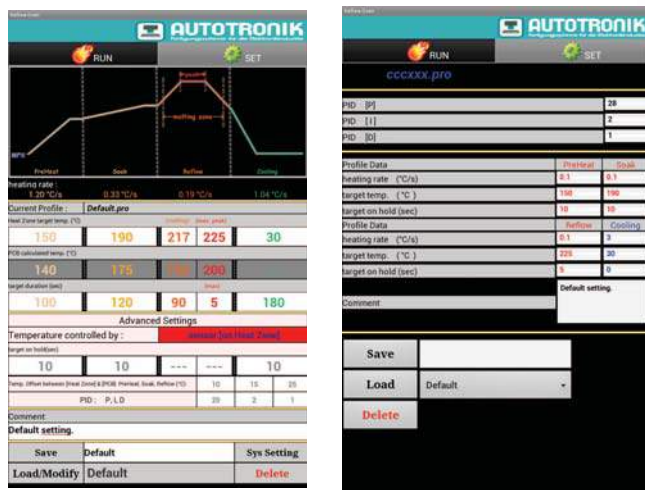
Match your thermal process specifications for preheat, soak, reflow, and cooling on the first PCB you produce with by using revolutionary new BT301 Batch Reflow Oven. Having the thermal conditions of an inline reflow system in a bench-top unit with a full dynamic thermal process.



The BT301 is ideal for product development, prototyping, and small series production. Solder profiles are easily set-up and stored through the control app of the BT301's exclusive hardware control and Android operating system. The dynamic control system takes care of size and complexity of your assembly and makes it a closed loop process, something only large and costly thermal systems can normally offer.

Features

- ◎ Real time close loop PID temperature control for leadfree profile
- ◎ Quick Smart programming by rising rate control (degree change per second)
- ◎ Infrared and forced convection combine for efficient lead-free reflow
- ◎ Real time temperature profile display
- ◎ Android system on multi-core CPU platform
- ◎ 7" touch screen high resolution LCD display
- ◎ Compact design ideal for labs, schools, prototyping and low-volume job shops
- ◎ WiFi temperature profile printing and data storage



Real-Time dynamic thermal Control via On-Board measuring device

The BT301 has an advanced setting in which you can turn on the real time dynamic process. The unit can then via real-time feedback from the measuring system which is attached at a strategic location on the PCB surface.

The heater control and fan speed is based on the actual temperature measured on the product. The target temperature is equal to the dynamic measuring system temperature and there is no offset, making this a perfect tool for prototyping and small series.

Specification

Machine Model

Applicable solder types
 PCB holding size
 PCB effective heating area
 Heating method
 Temperature range
 Temperature control method

Warm-up time
 Computer control
 Display panel
 Temperature control setting

Temperature profile display
 Temp profile printing
 Storage
 Electrical
 Power
 Dimensions
 Weight

BT301

Lead-Free and Leaded
 350 mm x 240 mm
 250 mm x 200 mm
 Quartz IR & Forced Hot Air Convection
 Ambient - 310 °C
 Real time close loop PID temperature control for lead free profile
 approx. 2 min.
 Build-in dual core CPU on board computer
 7" touch screen high resolution LCD display
 Quick smart profile programming by temperature rising rate control (degree change per second)
 Real time temperature profile display
 WiFi temperature profile printing
 External data storage via WiFi connection
 220 V, Single Phase, 50/60 Hz, 15A
 3000W
 690 mm L x 470 mm W x 270 mm H
 approx. 45 Kg

* We reserve the right to make changes without notice.